Amplifier Transistor

NPN Silicon

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--------------------------------|------------------|-------|------|
| Collector - Emitter Voltage | V_{CEO} | 25 | Vdc |
| Collector - Base Voltage | V_{CBO} | 40 | Vdc |
| Emitter-Base Voltage | V _{EBO} | 4.0 | Vdc |
| Collector Current — Continuous | I _C | 100 | mAdc |

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|---|-----------------------------------|-------------|-------------|
| Total Device Dissipation FR-5 Board (Note 1) @T _A = 25°C Derate above 25°C | P _D | 225 1.8 | mW mW/°C |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 556 | °C/W |
| Total Device Dissipation Alumina Substrate, (Note 2) @T _A = 25°C Derate above 25°C | P _D | 300 2.4 | mW mW/°C |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 417 | °C/W |
| Junction and Storage Temperature | T _J , T _{stg} | -55 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.

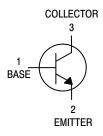


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SOT-23 (TO-236) CASE 318-08 STYLE 6



MARKING DIAGRAM



RO = Specific Device Code M = Date Code*

■ = Date Code = Pb–Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|---------------|---------------------|------------------------|
| MMBT6521LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| SMMBT6521LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
|--|----------------------|------------|----------|------|
| OFF CHARACTERISTICS | | | | |
| Collector – Emitter Breakdown Voltage ($I_C = 0.5 \text{ mAdc}, I_B = 0$) | V _{(BR)CEO} | 25 | _ | Vdc |
| Emitter – Base Breakdown Voltage ($I_E = 10 \mu Adc$, $I_C = 0$) | V _{(BR)EBO} | 4.0 | - | Vdc |
| Collector Cutoff Current (V _{CB} = 30 Vdc, I _E = 0) | Ісво | - | 0.5 | μAdc |
| Emitter Cutoff Current (V _{EB} = 5.0 Vdc, I _C = 0) | I _{EBO} | - | 10 | nAdc |
| ON CHARACTERISTICS | | | | |
| DC Current Gain $ (I_C = 100 \mu \text{Adc}, V_{CE} = 10 \text{Vdc}) $ $ (I_C = 2.0 \text{mAdc}, V_{CE} = 10 \text{Vdc}) $ | h _{FE} | 150 300 | - 600 | _ |
| Collector – Emitter Saturation Voltage (I _C = 50 mAdc, I _B = 5.0 mAdc) | V _{CE(sat)} | _ | 0.5 | Vdc |
| SMALL-SIGNAL CHARACTERISTICS | | | | |
| Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz) | C _{obo} | - | 3.5 | pF |
| Noise Figure (I_C = 10 μ Adc, V_{CE} = 5.0 Vdc, Power Bandwidth = 15.7 kHz, 3.0 dB points @ = 10 Hz and 10 kHz) | NF | - | 3.0 | dB |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

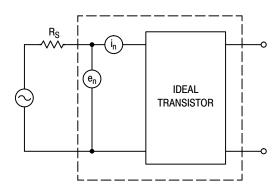


Figure 1. Transistor Noise Model

EQUIVALENT SWITCHING TIME TEST CIRCUITS

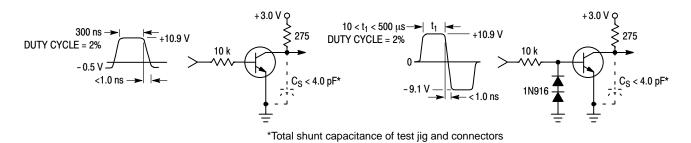


Figure 2. Turn-On Time

Figure 3. Turn-Off Time

TYPICAL NOISE CHARACTERISTICS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$

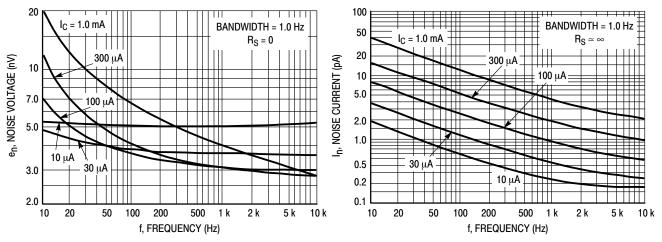


Figure 4. Noise Voltage

Figure 5. Noise Current

NOISE FIGURE CONTOURS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$

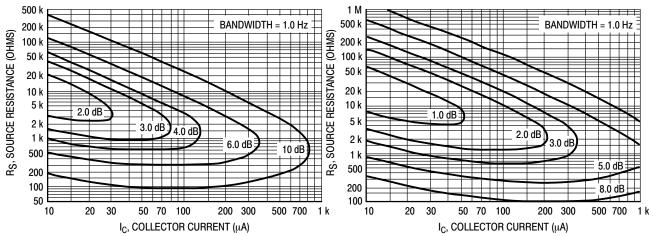
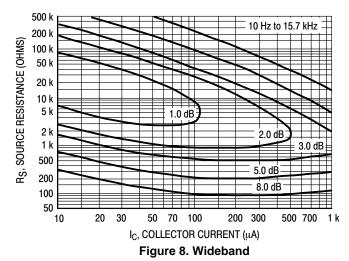


Figure 6. Narrow Band, 100 Hz

Figure 7. Narrow Band, 1.0 kHz



Noise Figure is defined as:

$$NF = 20 \log_{10} \left(\frac{e_n^2 + 4KTR_S + I_n^2 R_S^2}{4KTR_S} \right)^{1/2}$$

e_n = Noise Voltage of the Transistor referred to the input. (Figure 3)

In = Noise Current of the Transistor referred to the input. (Figure 4)

 $K = Boltzman's Constant (1.38 x <math>10^{-23} j/^{\circ}K)$

T = Temperature of the Source Resistance (°K)

R_S = Source Resistance (Ohms)

TYPICAL STATIC CHARACTERISTICS

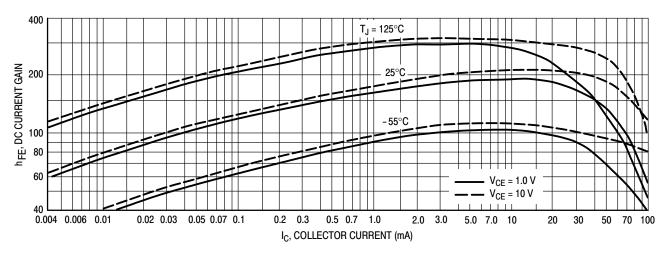


Figure 9. DC Current Gain

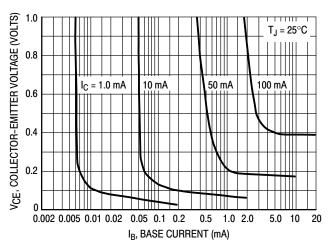


Figure 10. Collector Saturation Region

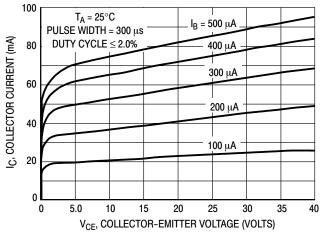


Figure 11. Collector Characteristics

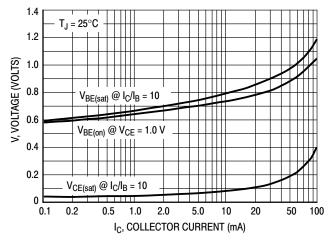


Figure 12. "On" Voltages

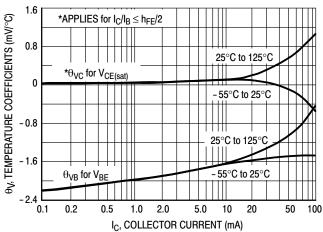
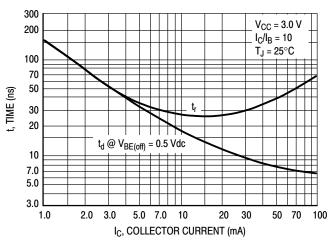


Figure 13. Temperature Coefficients

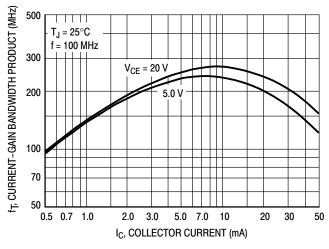
TYPICAL DYNAMIC CHARACTERISTICS



1000 700 500 300 200 t, TIME (ns) 100 70 50 $V_{CC} = 3.0 \text{ V}$ 30 $I_C/I_B = 10$ 20 $I_{B1} = I_{B2}$ $T_J = 25^{\circ}C$ 5.0 7.0 1.0 2.0 3.0 30 70 100 IC, COLLECTOR CURRENT (mA)

Figure 14. Turn-On Time

Figure 15. Turn-Off Time



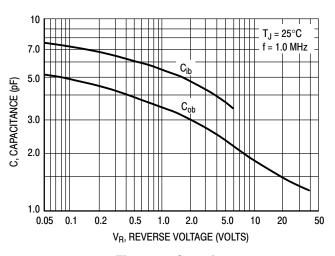
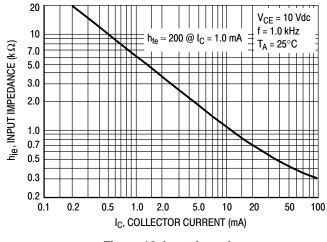


Figure 16. Current-Gain — Bandwidth Product

Figure 17. Capacitance



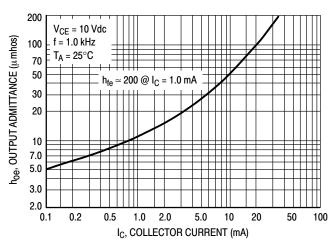


Figure 18. Input Impedance

Figure 19. Output Admittance

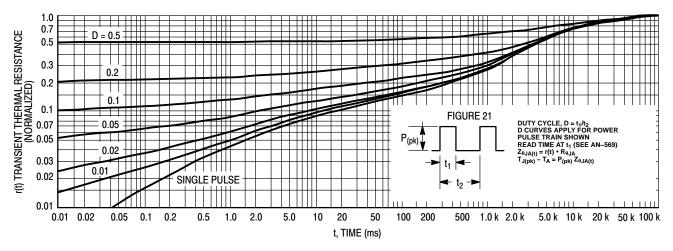


Figure 20. Thermal Response

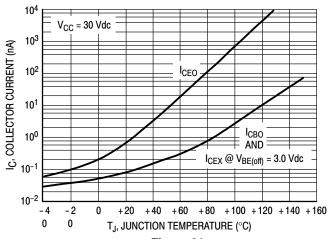


Figure 21.

DESIGN NOTE: USE OF THERMAL RESPONSE DATA

A train of periodical power pulses can be represented by the model as shown in Figure 21. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 20 was calculated for various duty cycles.

To find $Z_{\theta JA(t)}$, multiply the value obtained from Figure 20 by the steady state value $R_{\theta JA}$.

Example:

The MPS6521 is dissipating 2.0 watts peak under the following conditions:

$$t_1 = 1.0 \text{ ms}, t_2 = 5.0 \text{ ms}. (D = 0.2)$$

Using Figure 20 at a pulse width of 1.0 ms and D = 0.2, the reading of r(t) is 0.22.

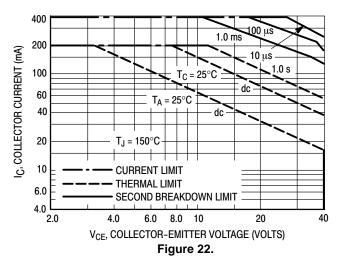
The peak rise in junction temperature is therefore

$$\Delta T = r(t) \times P_{(pk)} \times R_{\theta JA} = 0.22 \times 2.0 \times 200 = 88^{\circ}C.$$

For more information, see ON Semiconductor Application Note AN569/D, available from the Literature Distribution Center or on our website at **www.onsemi.com**.

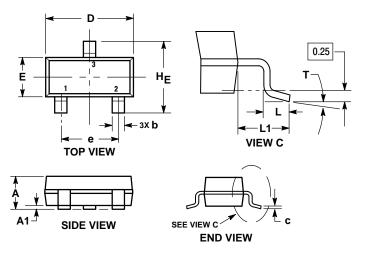
The safe operating area curves indicate I_C – V_{CE} limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 22 is based upon $T_{J(pk)} = 150^{\circ}C$; T_C or T_A is variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^{\circ}C$. $T_{J(pk)}$ may be calculated from the data in Figure 20. At high case or ambient temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.



PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR**



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
- THE BASE MATERIAL.

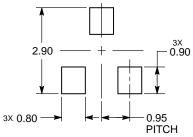
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR GATE BURRS.

| | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|-------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 0.89 | 1.00 | 1.11 | 0.035 | 0.039 | 0.044 |
| A1 | 0.01 | 0.06 | 0.10 | 0.000 | 0.002 | 0.004 |
| b | 0.37 | 0.44 | 0.50 | 0.015 | 0.017 | 0.020 |
| С | 0.08 | 0.14 | 0.20 | 0.003 | 0.006 | 0.008 |
| D | 2.80 | 2.90 | 3.04 | 0.110 | 0.114 | 0.120 |
| E | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| е | 1.78 | 1.90 | 2.04 | 0.070 | 0.075 | 0.080 |
| L | 0.30 | 0.43 | 0.55 | 0.012 | 0.017 | 0.022 |
| L1 | 0.35 | 0.54 | 0.69 | 0.014 | 0.021 | 0.027 |
| HE | 2.10 | 2.40 | 2.64 | 0.083 | 0.094 | 0.104 |
| Т | 0° | | 10° | 0° | | 10° |

STYLE 6:

- PIN 1. BASE
 - **EMITTER**
 - COLLECTOR

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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